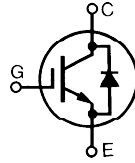


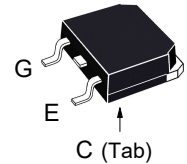
**High Voltage, High Gain
BIMOSFET™ Monolithic
Bipolar MOS Transistor**

**IXBT12N300
IXBH12N300**

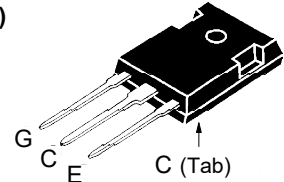
$V_{CES} = 3000V$
 $I_{C110} = 12A$
 $V_{CE(sat)} \leq 3.2V$



TO-268
(IXBT)



TO-247
(IXBH)



G = Gate C = Collector
E = Emitter Tab = Collector

| Symbol | Test Conditions | Maximum Ratings | |
|-------------------------------|--|-----------------------|------------|
| V_{CES} | $T_C = 25^\circ C$ to $150^\circ C$ | 3000 | V |
| V_{CGR} | $T_J = 25^\circ C$ to $150^\circ C$, $R_{GE} = 1M\Omega$ | 3000 | V |
| V_{GES} | Continuous | ± 20 | V |
| V_{GEM} | Transient | ± 30 | V |
| I_{C25} | $T_C = 25^\circ C$ | 30 | A |
| I_{C110} | $T_C = 110^\circ C$ | 12 | A |
| I_{CM} | $T_C = 25^\circ C$, 1ms | 100 | A |
| SSOA (RBSOA) | $V_{GE} = 15V$, $T_{VJ} = 125^\circ C$, $R_G = 30\Omega$ Clamped Inductive Load | $I_{CM} = 98$ 1500 | A V |
| P_C | $T_C = 25^\circ C$ | 160 | W |
| T_J | | -55 ... +150 | $^\circ C$ |
| T_{JM} | | 150 | $^\circ C$ |
| T_{stg} | | -55 ... +150 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering | 300 | $^\circ C$ |
| T_{SOLD} | Plastic Body for 10s | 260 | $^\circ C$ |
| M_d | Mounting Torque (TO-247) | 1.13/10 | Nm/lb.in. |
| Weight | TO-268 | 4 | g |
| | TO-247 | 6 | g |

Features

- High Blocking Voltage
- International Standard Packages
- Anti-Parallel Diode
- Low Conduction Losses

Advantages

- Low Gate Drive Requirement
- High Power Density

Applications:

- Switched-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generators
- Capacitor Discharge Circuits
- AC Switches

| Symbol | Test Conditions ($T_J = 25^\circ C$ Unless Otherwise Specified) | Characteristic Values | | |
|---------------|---|-----------------------|------|--------------------|
| | | Min. | Typ. | Max. |
| BV_{CES} | $I_C = 250\mu A$, $V_{GE} = 0V$ | 3000 | | V |
| $V_{GE(th)}$ | $I_C = 250\mu A$, $V_{CE} = V_{GE}$ | 3.0 | | V |
| I_{CES} | $V_{CE} = 0.8 \cdot V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ C$ | | | 25 μA 1 mA |
| I_{GES} | $V_{CE} = 0V$, $V_{GE} = \pm 20V$ | | | ± 100 nA |
| $V_{CE(sat)}$ | $I_C = 12A$, $V_{GE} = 15V$, Note 1 $T_J = 125^\circ C$ | | 2.8 | 3.2 V |
| | | | 3.5 | V |

| Symbol Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified) | | Characteristic Values | | |
|--|--|-----------------------|------|--------------------|
| | | Min. | Typ. | Max. |
| g_{fs} | $I_C = 12\text{A}, V_{CE} = 10\text{V}$, Note 1 | 6.5 | 10.8 | S |
| C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | | 1290 | pF |
| C_{oes} | | | 56 | pF |
| C_{res} | | | 19 | pF |
| Q_g | $I_C = 12\text{A}, V_{GE} = 15\text{V}, V_{CE} = 1000\text{V}$ | | 62 | nC |
| Q_{ge} | | | 13 | nC |
| Q_{gc} | | | 8.5 | nC |
| $t_{d(on)}$ | Resistive Switching Times, $T_J = 25^\circ\text{C}$ $I_C = 12\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 1250\text{V}, R_G = 10\Omega$ | | 64 | ns |
| t_r | | | 140 | ns |
| $t_{d(off)}$ | | | 180 | ns |
| t_f | | | 540 | ns |
| $t_{d(on)}$ | Resistive Switching Times, $T_J = 125^\circ\text{C}$ $I_C = 12\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 1250\text{V}, R_G = 10\Omega$ | | 65 | ns |
| t_r | | | 395 | ns |
| $t_{d(off)}$ | | | 175 | ns |
| t_f | | | 530 | ns |
| R_{thJC} | TO-247 | | 0.78 | $^\circ\text{C/W}$ |
| R_{thCS} | | 0.21 | | $^\circ\text{C/W}$ |

Reverse Diode

| Symbol Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified) | | Characteristic Values | | |
|--|---|---|------|---------------|
| | | Min. | Typ. | Max. |
| V_F | $I_F = 12\text{A}, V_{GE} = 0\text{V}$ | | | 2.1 V |
| t_{rr} | $I_F = 6\text{A}, V_{GE} = 0\text{V}, -di_F/dt = 100\text{A}/\mu\text{s}$ | | 1.4 | μs |
| I_{RM} | | $V_R = 100\text{V}, V_{GE} = 0\text{V}$ | | 21 |

Note 1: Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

Littelfuse reserves the right to change limits, test conditions and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

| | | | | | | | | | |
|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

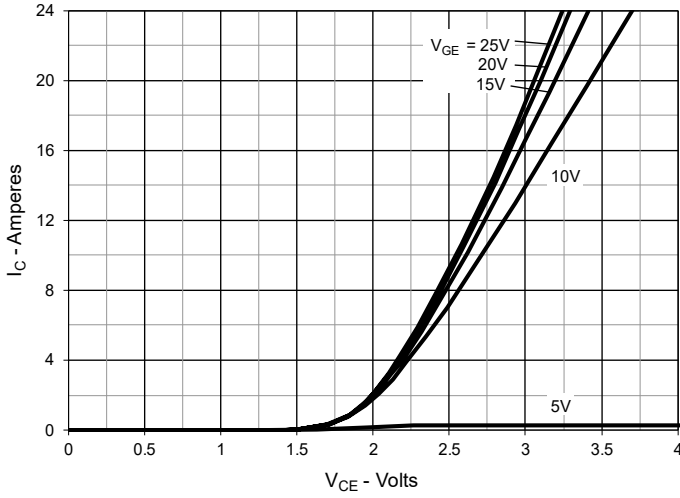


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

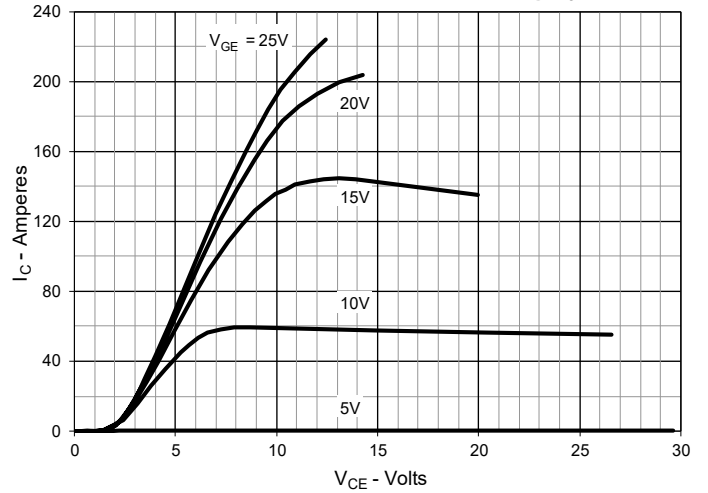


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

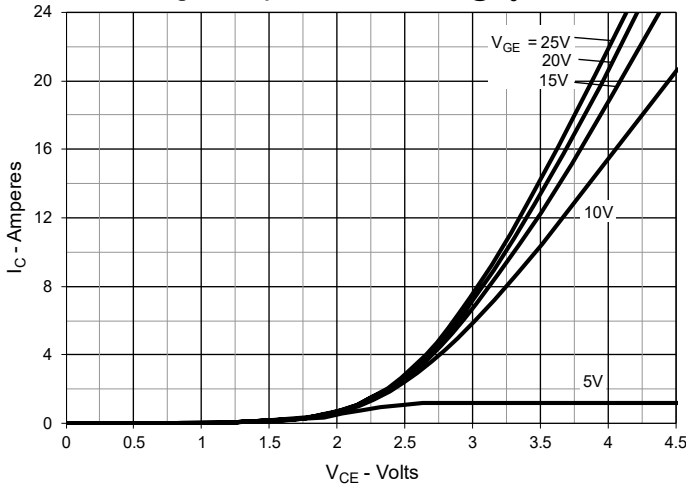


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

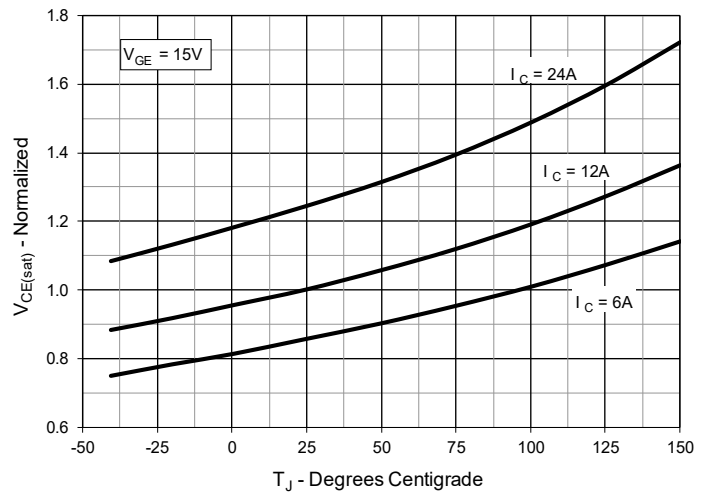


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

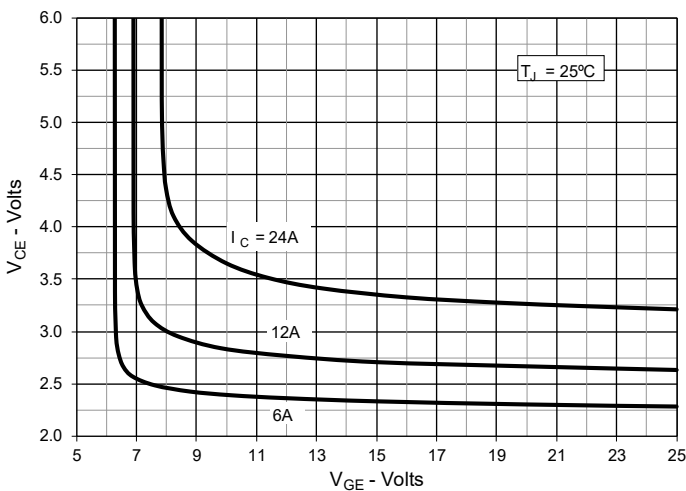


Fig. 6. Input Admittance

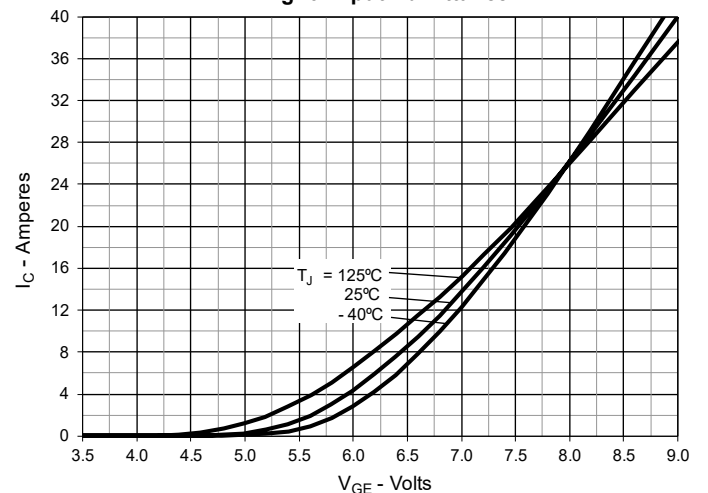


Fig. 7. Transconductance

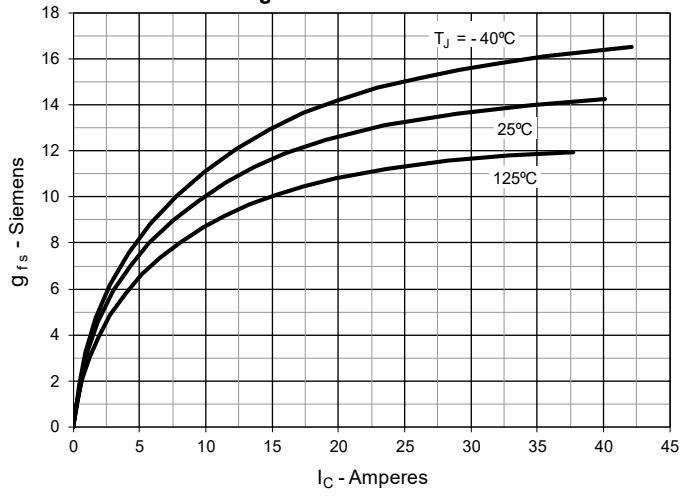


Fig. 8. Forward Voltage Drop of Intrinsic Diode

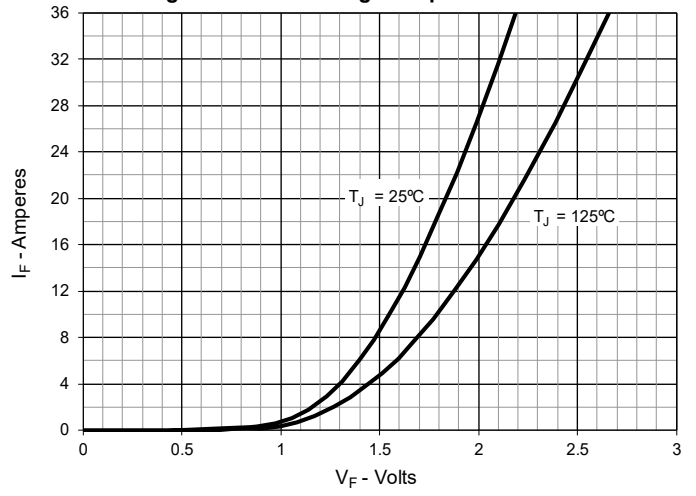


Fig. 9. Gate Charge

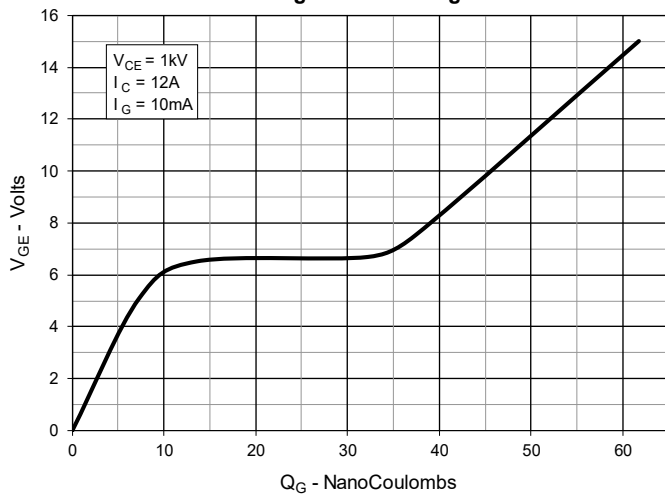


Fig. 10. Capacitance

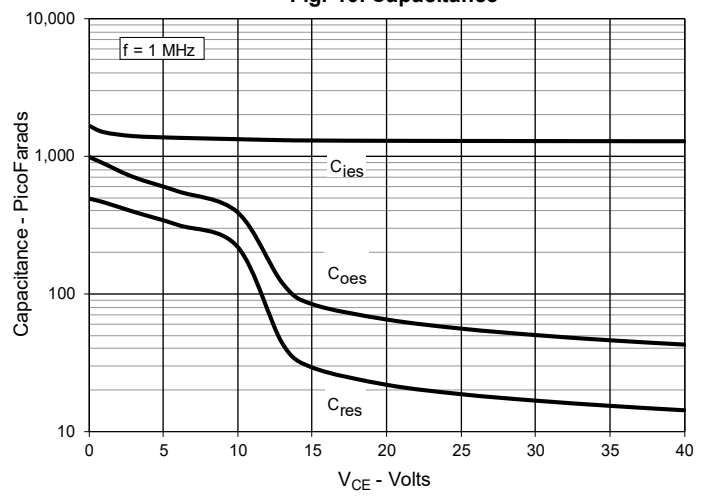


Fig. 11. Reverse-Bias Safe Operating Area

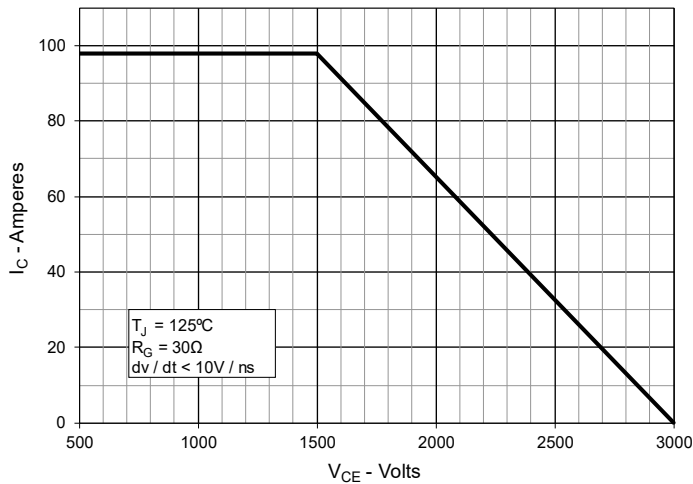


Fig. 12. Maximum Transient Thermal Impedance

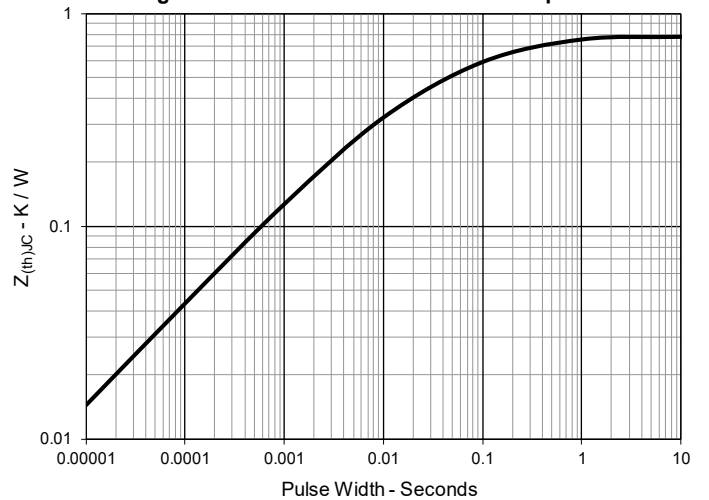


Fig. 15. Resistive Turn-on Rise Time vs. Junction Temperature

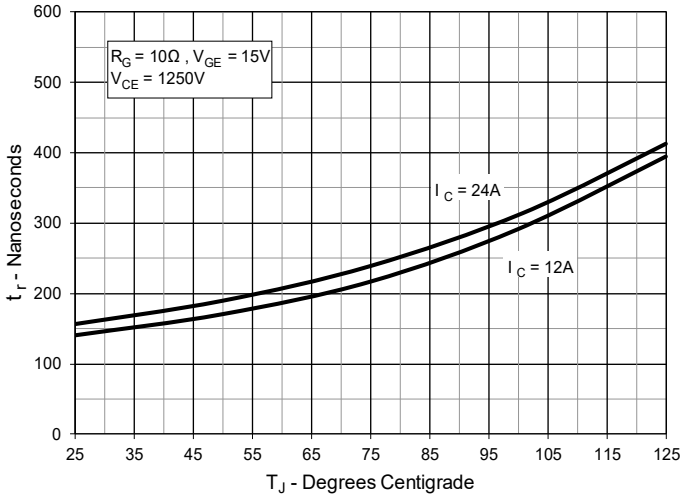


Fig. 16. Resistive Turn-on Rise Time vs. Collector Current

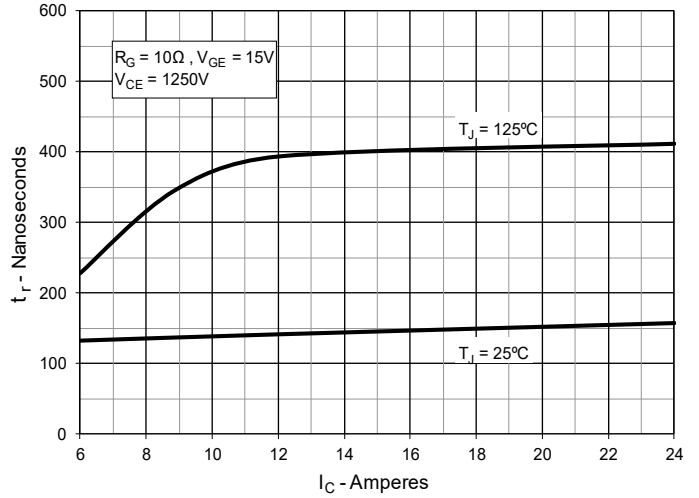


Fig. 17. Resistive Turn-off Switching Times vs. Gate Resistance

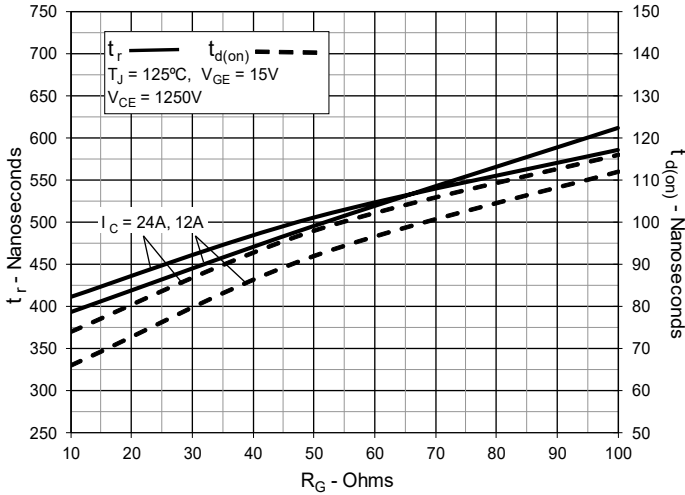


Fig. 18. Resistive Turn-off Switching Times vs. Junction Temperature

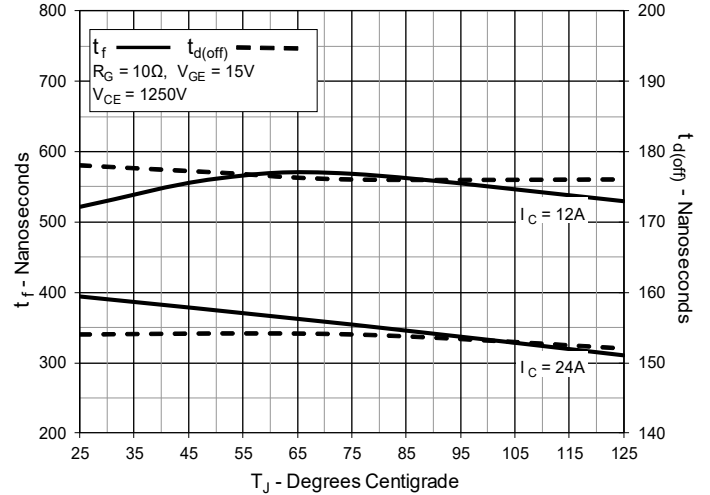


Fig. 19. Resistive Turn-off Switching Times vs. Collector Current

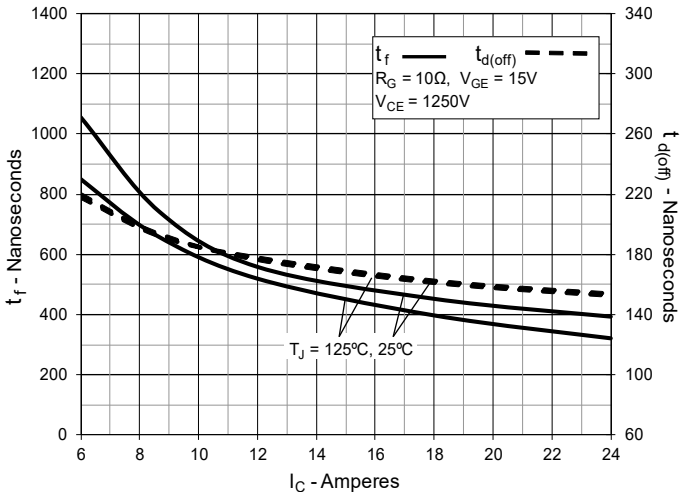
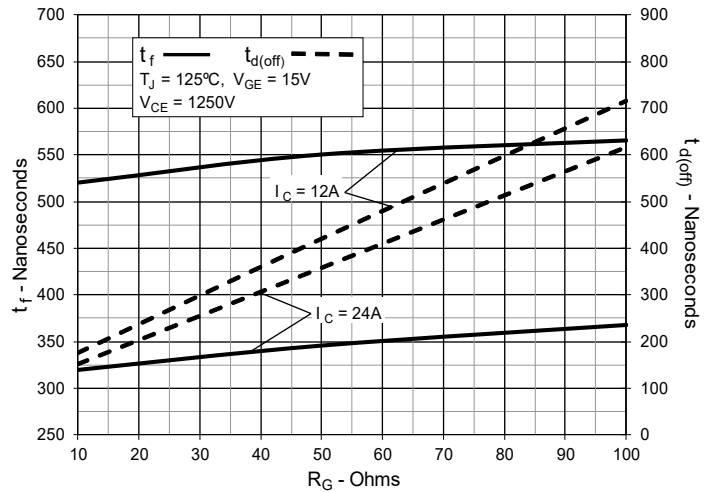
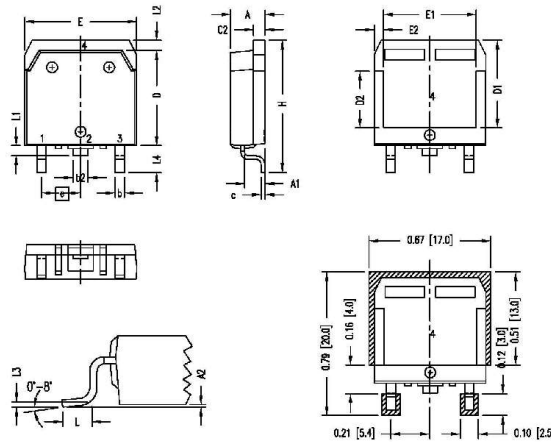


Fig. 20. Resistive Turn-off Switching Times vs. Gate Resistance



TO-268 Outline



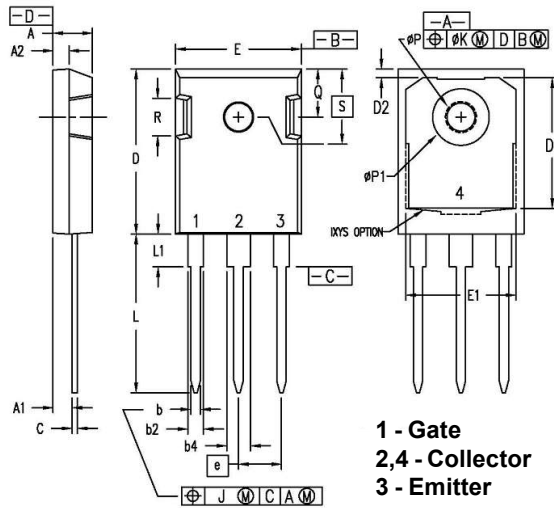
- 1 - Gate
- 2,4 - Collector
- 3 - Emitter

RECOMMENDED MINIMUM FOOT PRINT FOR SMD

| SYMBOL | INCHES | | MILLIMETERS | |
|--------|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .193 | .201 | 4.90 | 5.10 |
| A1 | .106 | .114 | 2.70 | 2.90 |
| A2 | .001 | .010 | 0.02 | 0.25 |
| b | .045 | .057 | 1.15 | 1.45 |
| b2 | .075 | .083 | 1.90 | 2.10 |
| C | .016 | .026 | 0.40 | 0.65 |
| C2 | .057 | .063 | 1.45 | 1.60 |
| D | .543 | .551 | 13.80 | 14.00 |
| D1 | .488 | .500 | 12.40 | 12.70 |
| D2 | .320 | .335 | 8.13 | 8.50 |
| E | .624 | .632 | 15.85 | 16.05 |
| E1 | .524 | .535 | 13.30 | 13.60 |
| E2 | .045 | .055 | 1.14 | 1.39 |
| e | .215 BSC | | 5.45 BSC | |
| H | .736 | .752 | 18.70 | 19.10 |
| L | .094 | .106 | 2.40 | 2.70 |
| L1 | .047 | .055 | 1.20 | 1.40 |
| L2 | .039 | .045 | 1.00 | 1.15 |
| L3 | .010 BSC | | 0.25 BSC | |
| L4 | .150 | .161 | 3.80 | 4.10 |

NOTE: ALL METAL SURFACE ARE MATTE PURE TIN PLATED EXCEPT TRIM AREA.
Pb PLATING THICKNESS (4 - 20 um)

TO-247 Outline



- 1 - Gate
- 2,4 - Collector
- 3 - Emitter

| SYM | INCHES | | MILLIMETERS | |
|-----|----------|----------|-------------|----------|
| | MIN | MAX | MIN | MAX |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .090 | .100 | 2.29 | 2.54 |
| A2 | .075 | .085 | 1.91 | 2.16 |
| b | .045 | .055 | 1.14 | 1.40 |
| b2 | .075 | .087 | 1.91 | 2.20 |
| b4 | .115 | .126 | 2.92 | 3.20 |
| C | .024 | .031 | 0.61 | 0.80 |
| D | .819 | .840 | 20.80 | 21.34 |
| D1 | .650 | .690 | 16.51 | 17.53 |
| D2 | .035 | .050 | 0.89 | 1.27 |
| E | .620 | .635 | 15.75 | 16.13 |
| E1 | .545 | .565 | 13.84 | 14.35 |
| e | .215 BSC | | 5.45 BSC | |
| J | -- | .010 | -- | 0.25 |
| K | -- | .025 | -- | 0.64 |
| L | .780 | .810 | 19.81 | 20.57 |
| L1 | .150 | .170 | 3.81 | 4.32 |
| øP | .140 | .144 | 3.55 | 3.65 |
| øP1 | .275 | .290 | 6.99 | 7.37 |
| Q | .220 | .244 | 5.59 | 6.20 |
| R | .170 | .190 | 4.32 | 4.83 |
| S | | .242 BSC | | 6.15 BSC |

NOTE: This drawing will meet all dimensions requirement of JEDEC outlines TO-247 AD (R-PSIP-F3)